

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Masakazu SHIMADA	04/20/2009
RECEIVING PARTY DATA	
Name:	Hitachi Kokusai Electric, Inc.
Street Address:	14-1 Sotokanda 4-chome, Chiyoda-ku
City:	Tokyo
State/Country:	JAPAN
Postal Code:	1018980
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12429462
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Total Attachments: 1 source=1006_Assignment#page1.tif	

OP \$40.00 12429462

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REEL: 022598 FRAME: 0583

ASSIGNMENT

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to the undersigned by Hitachi Kokusai Electric, Inc., a corporation organized under the laws of Japan, located at 14-1 Sotokanda 4-chome, Chiyoda-ku, Tokyo 1018980, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi Kokusai Electric, Inc., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SUBSTRATE PROCESSING APPARATUS, HEATING DEVICE AND SEMICONDUCTOR DEVICE MANUFACTURING METHOD

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi Kokusai Electric, Inc., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi Kokusai Electric, Inc.

Signed on the date(s) indicated aside signatures:

INVENTOR(S)

Date Signed

1) Masakazu Shimada

Masakazu Shimada

April 20, 2009

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